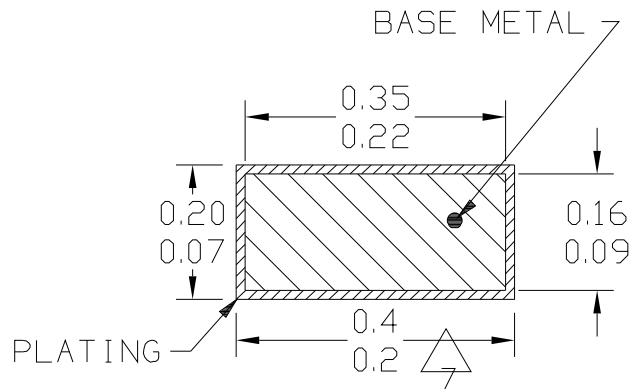
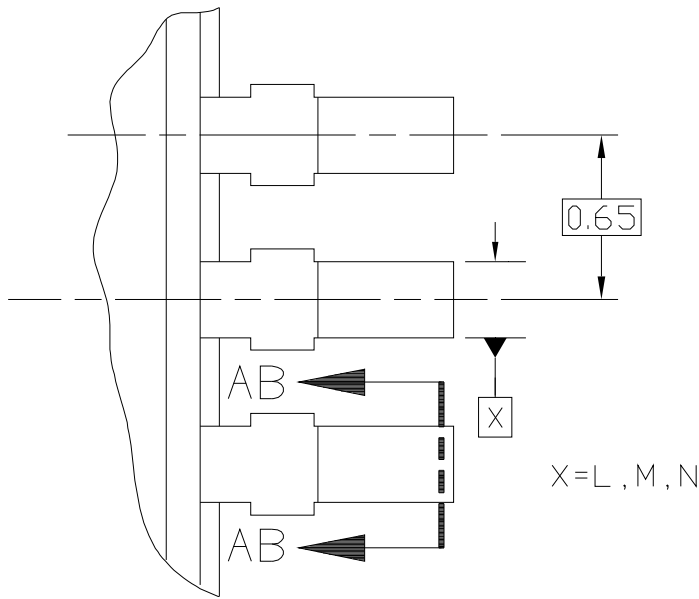
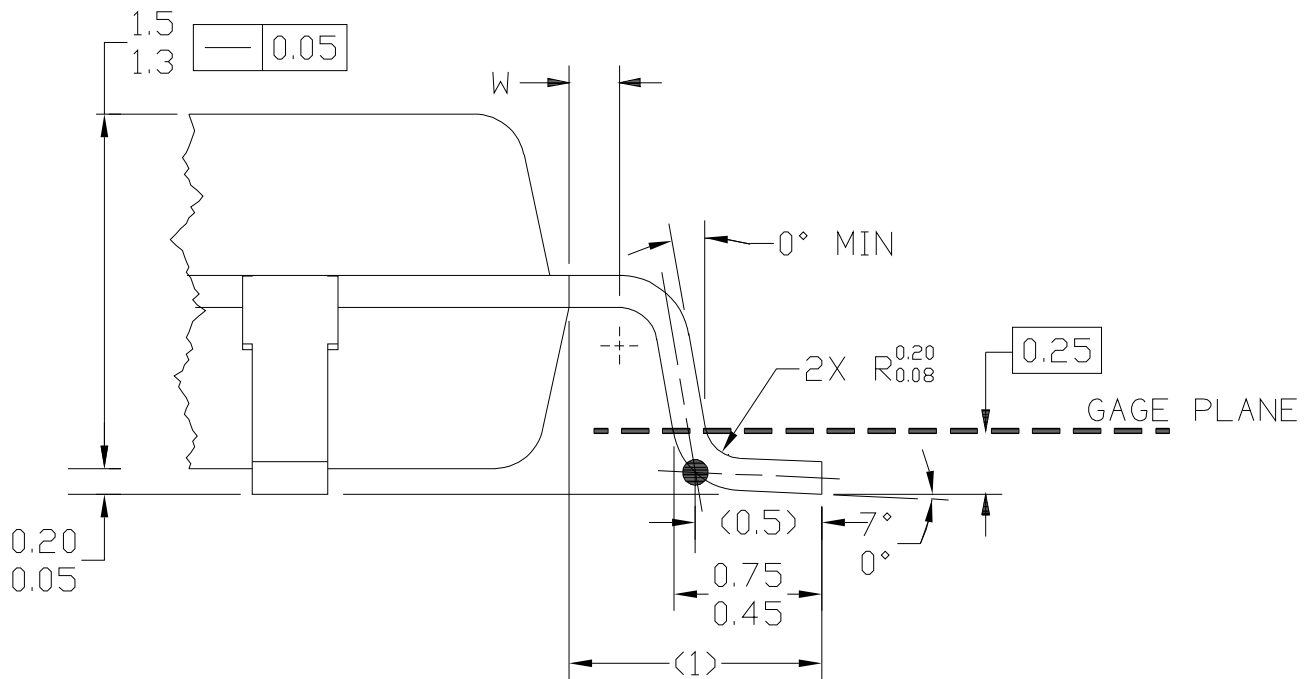


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TITLE: 52LD TQFP		DOCUMENT NO: 98ASS23228W	REV: G
10 X 10 PKG, 0.65 PITCH, 1.4 THICK		STANDARD: NON-JEDEC	
		SOT1671-1	25 JAN 2016



⊕ 0.13 ⊕ T L-M N

SECTION AB-AB
ROTATED 90° CLOCKWISE



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NOTES

1. DIMENSIONS AND TOLERANCING PER ASME Y14.5M. 1994.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DATUM PLANE H IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.
4. DATUMS L, M, AND N TO BE DETERMINED AT DATUM PLANE H.
5. DIMENSIONS TO BE DETERMINED AT SEATING PLANE T.
6. DIMENSIONS DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25 PER SIDE. DIMENSIONS DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE H.
7. DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED 0.46. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD OR PROTRUSION 0.07.

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